

High Speed PWM Controller

FEATURES

- Compatible with Voltage or Current-Mode Topologies
- Practical Operation @ Switching Frequencies to 1.0MHz
- 50ns Propagation Delay to Output
- High Current Totem Pole Output (1.5A peak)
- Wide Bandwidth Error Amplifier
- Fully Latched Logic with Double Pulse
 Suppression
- Pulse-by-Pulse Current Limiting
- Soft Start/Max. Duty Cycle Control
- Under-Voltage Lockout with Hysteresis
- Low Start Up Current (1.1mA)
- Trimmed Bandgap Reference (5.1V ±1%)

ABSOLUTE MAXIMUM RATINGS

Soft Start Sink Current (Pin 8) 20mA

BLOCK DIAGRAM

DESCRIPTION

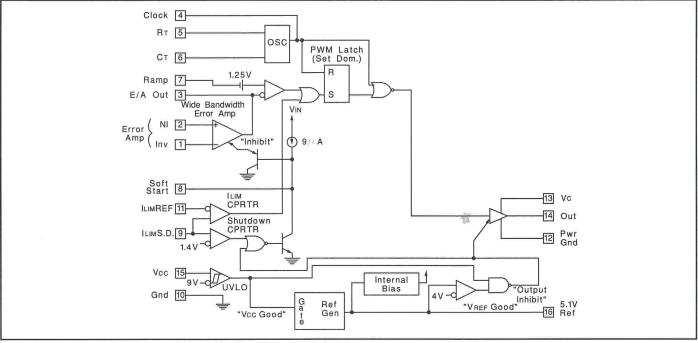
The UC1823 family of PWM control ICs is optimized for high frequency switched mode power supply applications. Particular care was given to minimizing propagation delays through the comparators and logic circuitry while maximizing bandwidth and slew rate of the error amplifier. This controller is designed for use in either current-mode or voltage-mode systems with the capability for input voltage feed-forward.

Protection circuitry includes a current limit comparator, a TTL compatible shutdown port, and a soft start pin which will double as a maximum duty cycle clamp. The logic is fully latched to provide jitter free operation and prohibit multiple pulses at the output. An under-voltage lockout section with 800mV of hysteresis assures low start up current. During under-voltage lockout, the output is high impedance. The current limit reference (pin 11) is a DC input voltage to the current limit comparator. Consult specifications for details.

These devices feature a totem pole output designed to source and sink high peak currents from capacitive loads, such as the gate of a power MOSFET. The on state is defined as a high level.

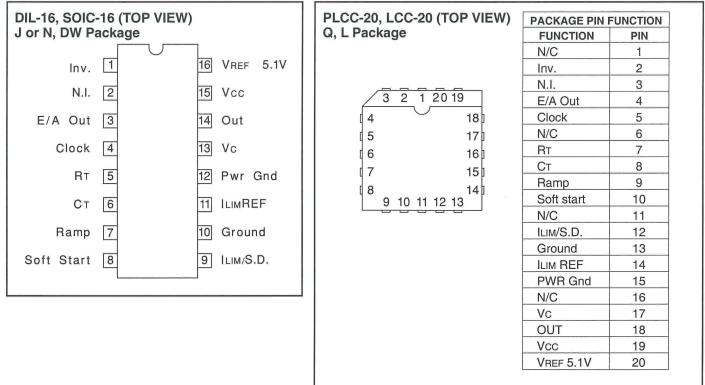
| Oscillator Charging Current (Pin 5)5mA | |
|--|--|
| Power Dissipation at T _A = 60 °C | |
| Storage Temperature Range65°C to +150°C | |
| Lead Temperature (Soldering, 10 seconds) 300°C | |
| Note: All voltages are with respect to ground, Pin 10. | |
| Currents are positive into the specified terminal | |

Currents are positive into the specified terminal. Consult Packaging Section of Databook for thermal limitations



SLUS219B - MARCH 1997 - REVISED SEPTEMBER 2009

CONNECTION DIAGRAMS



THERMAL PACKAGING INFORMATION

| PACKAGE | θja | θ JC |
|-------------------|-----------------|-------------|
| J-16 | 80 - 120 | 28 (Note2) |
| N-16 | 90 (Note1) | 45 |
| DW-16 | 45 - 90 (Note1) | 25 |
| PLCC-20 Q Package | 43 - 75 (Note1) | 34 |
| LCC-20 LPackage | 70 - 80 | 20 (Note2) |

Note 1. Specified θ_{JA} (junction to ambient) is for devices mounted to 5-in-2 FR4 PC board with one ounce copper where noted. When resistance range is given, lower values are for 5-in-2 aluminum PC board. Test PWB was 0.062 in thick and typically used 0.635 mm trace widths for power pkgs and 1.3 mm trace widths for non-power pkgs with a 100 x 100 mil probe land area at the end of each trace.

Note 2. θ_{JC} data values stated were derived from MIL-STD-1835B. MIL-STD-1835B states that "The baseline values shown are worst case (mean + 2s) for a 60 x 60 mil microcircuit device silicon die and applicable for devices with die sizes up to 14400 square mils. For device die sizes greater than14400 square mils use the following values; dual-in-line, 11°C/W; flat pack, 10°C/W; pin grid array, 10°C/W"

ELECTRICAL CHARACTERISTICS: Unless otherwise noted, these specifications apply for RT = 3.65k, CT = 1nF, Vcc = 15V, 0°C < Ta < +70°C for the UC3823, -25°C < Ta < +85°C for the UC2823, and -55°C < Ta < +125°C for the UC1823, Ta = TJ.

| PARAMETER | TEST CONDITIONS | | UC1823 UC2823 | | | UNITS | | |
|-------------------------|--|------|------------------|------|------|-------|------|-------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | |
| Reference Section | | | | | | | | |
| Output Voltage | $T_{J} = 25^{\circ}C$, $I_{O} = 1mA$ | 5.05 | 5.10 | 5.15 | 5.00 | 5.10 | 5.20 | V |
| Line Regulation | 10 < Vcc < 30V | | 2 | 20 | | 2 | 20 | mV |
| Load Regulation | 1 < lo < 10mA | | 5 | 20 | | 5 | 20 | mV |
| Temperature Stability* | TMIN < TA < TMAX | | 0.2 | 0.4 | | 0.2 | 0.4 | mV/°C |
| Total Output Variation* | Line, Load, Temp. | 5.00 | | 5.20 | 4.95 | | 5.25 | |
| Output Noise Voltage* | 10Hz < f < 10kHz | | 50 | | | 50 | | μV |
| Long Term Stability* | TJ = 125°C, 1000 hrs. | | 5 | 25 | | 5 | 25 | mV |
| Short Circuit Current | VREF=0V | -15 | -50 | -100 | -15 | -50 | -100 | mA |
| Oscillator Section | | | | | | | | |
| Initial Accuracy* | TJ=25°C | 360 | 400 | 440 | 360 | 400 | 440 | kHz |
| Voltage Stability* | 10 < Vcc < 30V | | 0.2 | 2 | | 0.2 | 2 | % |
| Temperature Stability* | TMIN <ta (uc1823)<="" <="" td="" tmax=""><td></td><td>12</td><td></td><td></td><td></td><td></td><td>%</td></ta> | | 12 | | | | | % |
| | TMIN <ta (uc2823)<="" <="" td="" tmax=""><td></td><td>5</td><td></td><td></td><td></td><td></td><td>%</td></ta> | | 5 | | | | | % |
| | TMIN <ta (uc3823)<="" <="" td="" tmax=""><td></td><td></td><td></td><td></td><td>5</td><td></td><td>%</td></ta> | | | | | 5 | | % |
| Total Variation* | Line, Temp. | 340 | | 460 | 340 | | 460 | kHz |
| Clock Out High | | 3.9 | 4.5 | | 3.9 | 4.5 | | V |
| Clock Out Low | | | 2.3 | 2.9 | | 2.3 | 2.9 | V |
| Ramp Peak* | | 2.6 | 2.8 | 3.0 | 2.6 | 2.8 | 3.0 | V |
| Ramp Valley* | | 0.7 | 1.0 | 1.25 | 0.7 | 1.0 | 1.25 | V |
| Error Amplifier Section | t. | | | | | | | |
| Input Offset Voltage | | | | 10 | | | 15 | mV |
| Input Bias Current | | | 0.6 | 3 | | 0.6 | 3 | μA |
| Input Offset Current | | | 0.1 | 1 | | 0.1 | 1 | μA |
| Open Loop Gain | 1 < Vo < 4V | 60 | 95 | | 60 | 95 | | dB |
| CMRR | 1.5 < Vсм < 5.5V | 75 | 95 | | 75 | 95 | | dB |
| PSRR | 10 < VCC < 30V | 85 | 110 | | 85 | 110 | | dB |
| Output Sink Current | VPIN 3 =1V | 1 | 2.5 | | 1 | 2.5 | | mA |
| Output Source Current | VPIN 3 = 4V | -0.5 | -1.3 | | -0.5 | -1.3 | | mA |
| Output High Voltage | IPIN 3 = -0.5mA | 4.0 | 4.7 | 5.0 | 4.0 | 4.7 | 5.0 | V |
| Output Low Voltage | IPIN 3 = 1mA | 0 | 0.5 | 1.0 | 0 | 0.5 | 1.0 | V |
| Unity Gain Bandwidth* | | 3 | 5.5 | | 3 | 5.5 | | MHz |
| Slew Rate* | | 6 | 12 | | 6 | 12 | | V/µS |
| Ramp Valley to Peak* | | 1.6 | 1.8 | 2.0 | 1.6 | 1.8 | 2.0 | V |

* These parameters are ensured by design but not 100% tested in production.

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ELECTRICAL CHARACTERISTICS: Unless otherwise noted, these specifications apply for RT = 3.65k, CT = 1nF, Vcc = 15V, $0^{\circ}C < Ta < +70^{\circ}C$ for the UC3823, $-25^{\circ}C < Ta < +85^{\circ}C$ for the UC2823, and $-55^{\circ}C < Ta < +125^{\circ}C$ for the UC1823, Ta = TJ.

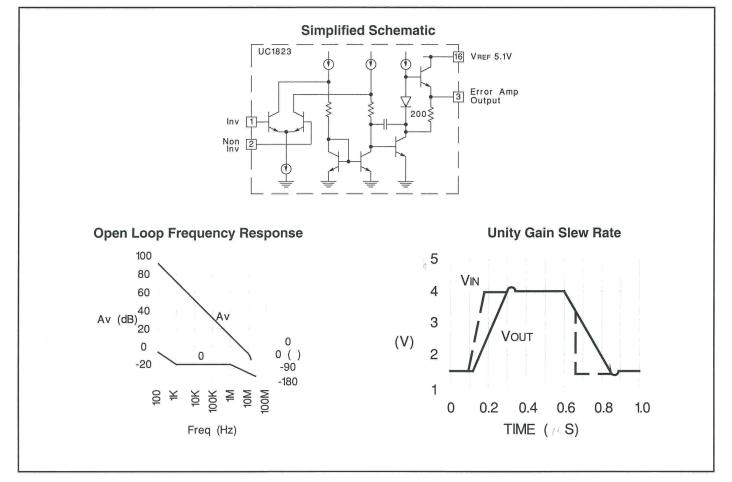
| PARAMETER | TEST CONDITIONS | | UC1823 UC2823 | | | UNITS | | |
|--|--|----------|------------------|------|------|-------|------|----|
| | | MIN | TYP | MAX | MIN | TYP | MAX | 1 |
| PWM Comparator Section | | | | | | | | |
| Pin 7 Bias Current | VPIN 7 = 0V | | -1 | -5 | | -1 | -5 | μA |
| Duty Cycle Range | | 0 | | 80 | 0 | | 85 | % |
| Pin 3 Zero D.C. Threshold | VPIN 7 = $0V$ | 1.1 | 1.25 | | 1.1 | 1.25 | | V |
| Delay to Output* | | | 50 | 80 | | 50 | 80 | ns |
| Soft-Start Section | r F | | | | | | | |
| Charge Current | V _{PIN 8} = 0.5V | 3 | 9 | 20 | 3 | 9 | 20 | μA |
| Discharge Current | VPIN 8 = 1V | 1 | | | 1 | | | mA |
| Current Limit/Shutdown Sectio | n | | | | | | | |
| Pin 9 Bias Current | 0 < VPIN 9 < 4V | | | ±10 | | | ±10 | μA |
| Current Limit Offset | VPIN 11 = 1.1V | | | 15 | | | 15 | mV |
| Current Limit Common Mode Range (VPIN 11) | | 1.0 | | 1.25 | 1.0 | | 1.25 | V |
| Shutdown Threshold | | 1.25 | 1.40 | 1.55 | 1.25 | 1.40 | 1.55 | V |
| Delay to Output* | | | 50 | 80 | | 50 | 80 | ns |
| Output Section | | | | | | | | |
| Output Low Level | IOUT = 20mA | | 0.25 | 0.40 | | 0.25 | 0.40 | V |
| | IOUT = 200mA | <i>,</i> | 1.2 | 2.2 | | 1.2 | 2.2 | V |
| Output High Level | 10UT = -20mA | 13.0 | 13.5 | | 13.0 | 13.5 | | V |
| | IOUT = -200mA | 12.0 | 13.0 | | 12.0 | 13.0 | | V |
| Collector Leakage | Vc = 30V | | 100 | 500 | | 100 | 500 | μΑ |
| Rise/Fall Time* | CL = 1nF | | 30 | 60 | | 30 | 60 | ns |
| Under-Voltage Lockout Section | | | | | | | | |
| Start Threshold | | 8.8 | 9.2 | 9.6 | 8.8 | 9.2 | 9.6 | V |
| UVLO Hysteresis | | 0.4 | 0.8 | 1.2 | 0.4 | 0.8 | 1.2 | V |
| Supply Current | | | | | | | | |
| Start Up Current | Vcc = 8V | | 1.1 | 2.5 | | 1.1 | 2.5 | mA |
| lcc | VPIN 1, VPIN 7, VPIN 9 = 0V, VPIN 2 = 1V | | 22 | 33 | | 22 | 33 | mA |

* These parameters are ensured by design but not 100% tested in production.

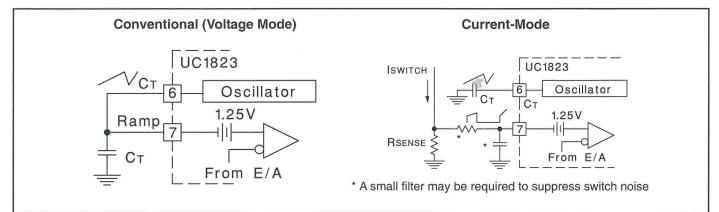
UC1823 PRINTED CIRCUIT BOARD LAYOUT CONSIDERATIONS

High speed circuits demand careful attention to layout and component placement. To assure proper performance of the UC1823, follow these rules. 1) Use a ground plane. 2) Damp or clamp parasitic inductive kick energy from the gate of driven MOSFET. Don't allow the output pins to ring below ground. A series gate resistor or a shunt 1 Amp Schottky diode at the output pin will serve this purpose. 3) Bypass Vcc, Vc, and VREF. Use 0.1μ F monolithic ceramic capacitors with low equivalent series inductance. Allow less than 1 cm of total lead length for each capacitor between the bypassed pin and the ground plane. 4) Treat the timing capacitor, CT, like a bypass capacitor.

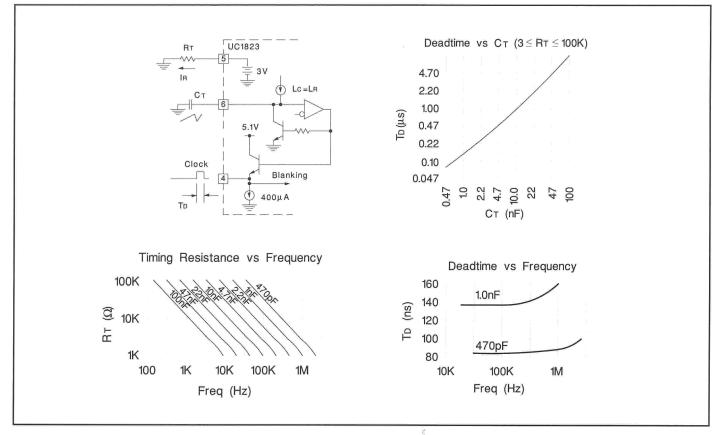
ERROR AMPLIFIER CIRCUIT



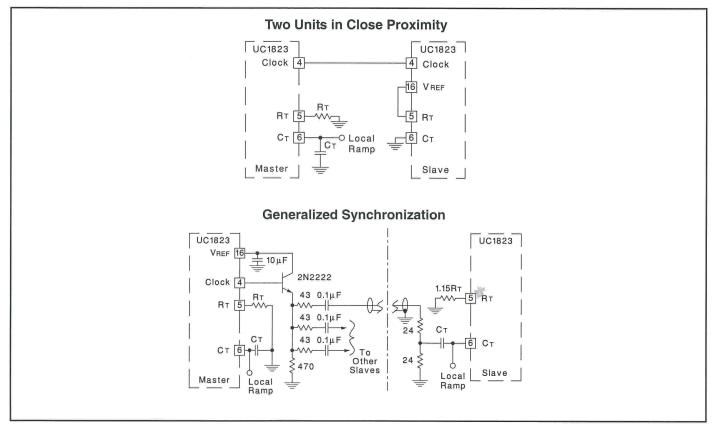
PWM APPLICATIONS



OSCILLATOR CIRCUIT

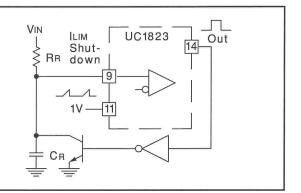


SYNCHRONIZED OPERATION

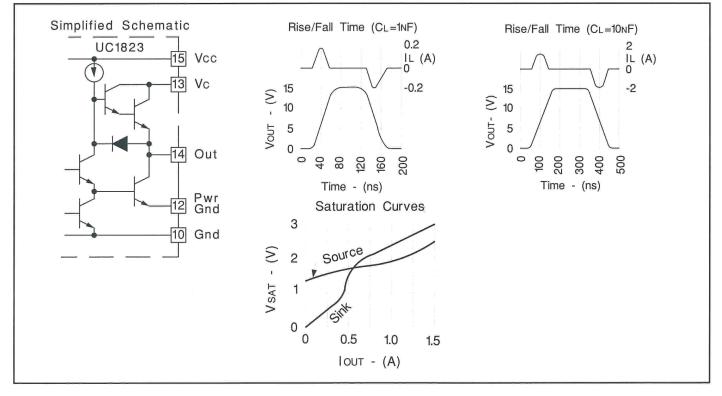


CONSTANT VOLT-SECOND CLAMP CIRCUIT

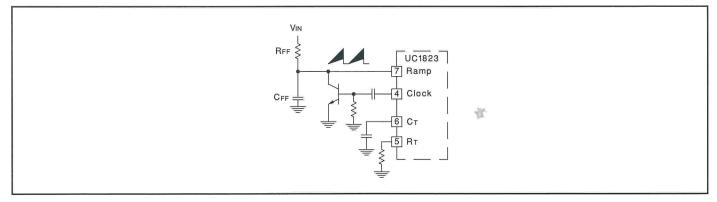
The circuit shown here will achieve a constant volt-second product clamp over varying input voltages. The ramp generator components, RT and CR are chosen so that the ramp at Pin 9 crosses the 1V threshold at the same time the desired maximum volt-second product is reached. The delay through the inverter must be such that the ramp capacitor can be completely discharged during the minimum deadtime.



OUTPUT SECTION



FEED FORWARD TECHNIQUE FOR OFF-LINE VOLTAGE MODE APPLICATION





PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|---------------------|--------------------------------------|----------------------|--------------|--|---------|
| 5962-89905012A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 89905012A UC1823L/ 883B | Samples |
| 5962-8990501EA | ACTIVE | CDIP | J | 16 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8990501EA UC1823J/883B | Samples |
| UC1823J | ACTIVE | CDIP | J | 16 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | UC1823J | Samples |
| UC1823J883B | ACTIVE | CDIP | J | 16 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8990501EA UC1823J/883B | Samples |
| UC1823L | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | UC1823L | Samples |
| UC1823L883B | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 89905012A UC1823L/ 883B | Samples |
| UC2823DW | ACTIVE | SOIC | DW | 16 | 40 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -25 to 85 | UC2823DW | Samples |
| UC2823DWTR | ACTIVE | SOIC | DW | 16 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -25 to 85 | UC2823DW | Samples |
| UC2823N | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -25 to 85 | UC2823N | Samples |
| UC3823DW | ACTIVE | SOIC | DW | 16 | 40 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3823DW | Samples |
| UC3823DWG4 | ACTIVE | SOIC | DW | 16 | 40 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3823DW | Samples |
| UC3823DWTR | ACTIVE | SOIC | DW | 16 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | 0 to 70 | UC3823DW | Samples |
| UC3823N | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | UC3823N | Samples |
| UC3823NG4 | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | UC3823N | Samples |

(1) The marketing status values are defined as follows:
 ACTIVE: Product device recommended for new designs.
 LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
 NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
 PREVIEW: Device has been announced but is not in production. Samples may or may not be available.



OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF UC1823, UC3823 :

Catalog : UC3823

• Military : UC1823

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| *All dimensions are nominal | | | | | | | | | | | | |
|-----------------------------|------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| Device | - | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
| UC2823DWTR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |
| UC3823DWTR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| UC2823DWTR | SOIC | DW | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| UC3823DWTR | SOIC | DW | 16 | 2000 | 356.0 | 356.0 | 35.0 |

TEXAS INSTRUMENTS

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3-Jun-2022

TUBE



- B - Alignment groove width

| *All dimensions are nominal |
|-----------------------------|
|-----------------------------|

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | Τ (μm) | B (mm) |
|----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-89905012A | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| UC1823L | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| UC1823L883B | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| UC2823DW | DW | SOIC | 16 | 40 | 507 | 12.83 | 5080 | 6.6 |
| UC2823N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| UC3823DW | DW | SOIC | 16 | 40 | 507 | 12.83 | 5080 | 6.6 |
| UC3823DWG4 | DW | SOIC | 16 | 40 | 507 | 12.83 | 5080 | 6.6 |
| UC3823N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| UC3823NG4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |

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